

HAT2240C

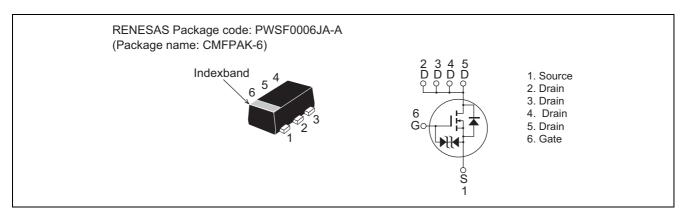
Silicon N Channel MOS FET Power Switching

REJ03G1241-0400 Rev.4.00 Apr 05, 2006

Features

- Low on-resistance $R_{DS(on)} = 75 \ m\Omega \ typ. (at \ V_{GS} = 4.5 \ V)$
- Low drive current
- High density mounting
- 2.5 V gate drive device

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V _{GSS}	±12	V
Drain current	I _D	2.5	А
Drain peak current	I _{D (pulse)} Note1	10	А
Body - drain diode reverse drain current	I _{DR}	2.5	А
Channel dissipation	Pch Note2	900	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board (FR4 40 x 40 x 1.6mm)

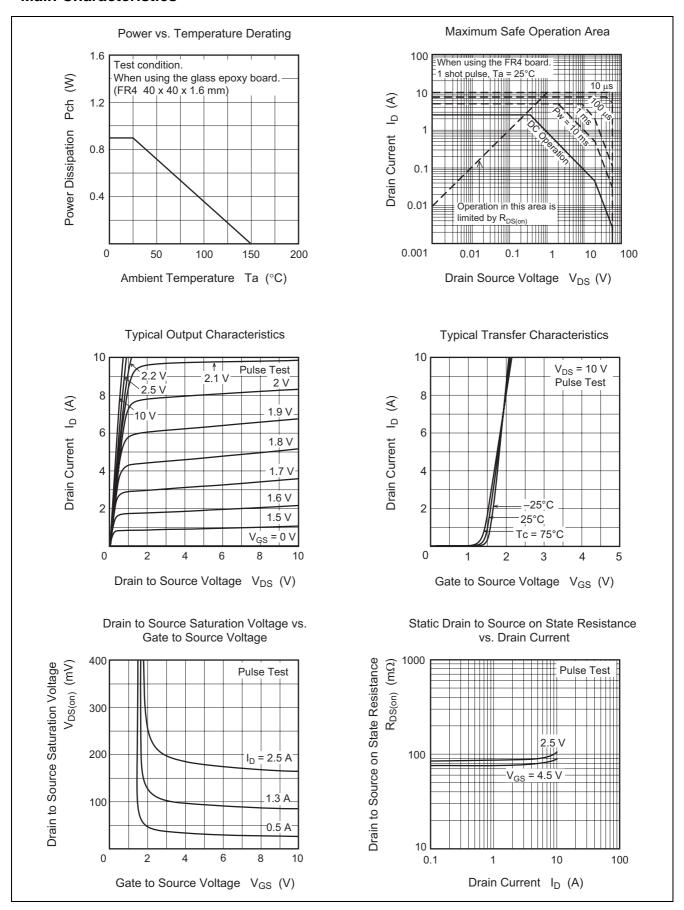
Electrical Characteristics

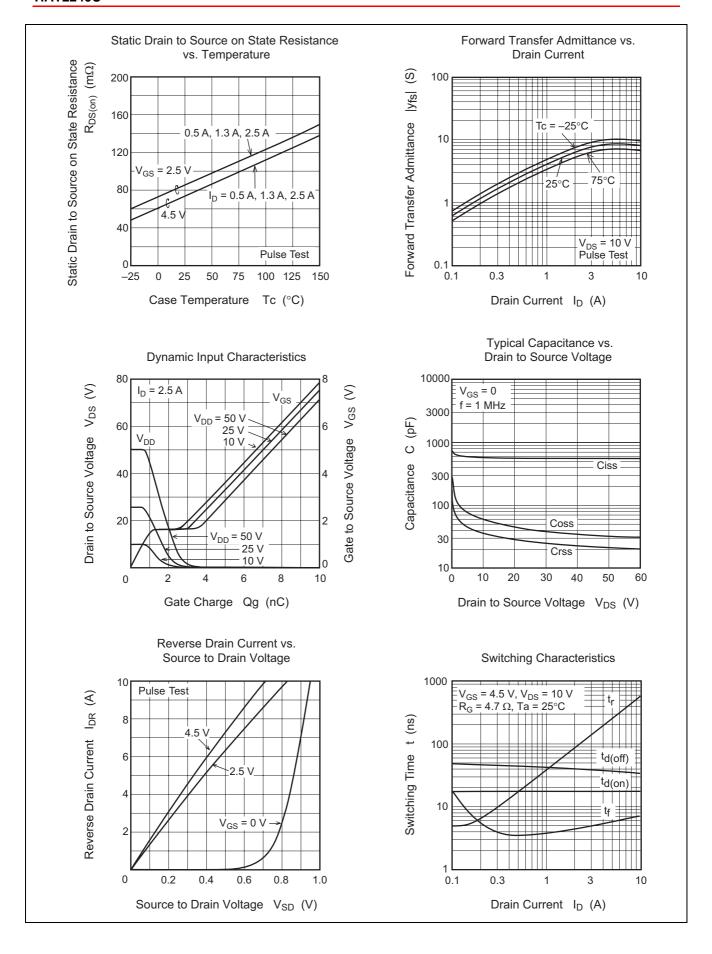
 $(Ta = 25^{\circ}C)$

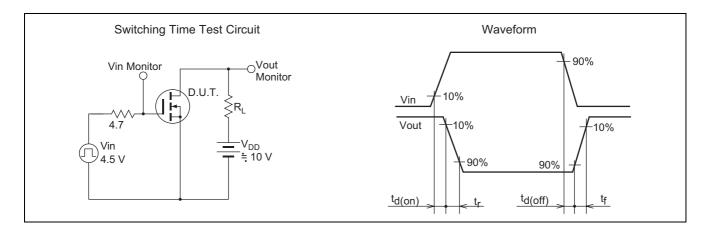
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±12				$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Drain to source leak current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	0.4	_	1.4	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Drain to source on state resistance	R _{DS(on)}	_	75	98	mΩ	$I_D = 1.3 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
	R _{DS(on)}	_	85	119	mΩ	$I_D = 1.3 \text{ A}, V_{GS} = 2.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	yfs	3.3	5	_	S	$I_D = 1.3 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	590	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	60	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	35	_	pF	
Turn - on delay time	td(on)	_	17	_	ns	I _D = 1.3 A
Rise time	tr	_	50	_	ns	$V_{GS} = 4.5 \text{ V}, V_{DD} = 10 \text{ V}$
Turn - off delay time	td(off)	_	41	_	ns	$R_L = 7.7 \Omega$, $Rg = 4.7 \Omega$
Fall time	tf	_	4	_	ns	
Total gate charge	Qg	_	6	_	nC	V _{DD} = 10 V, V _{GS} = 4.5 V
Gate to source charge	Qgs	_	1.2	_	nC	I _D = 2.5 A
Gate to drain charge	Qgd	_	1.4	_	nC	
Body - drain diode forward voltage	V_{DF}	_	8.0	1.1	V	$I_F = 2.5 \text{ A}, V_{GS} = 0^{\text{Note3}}$

Notes: 3. Pulse test

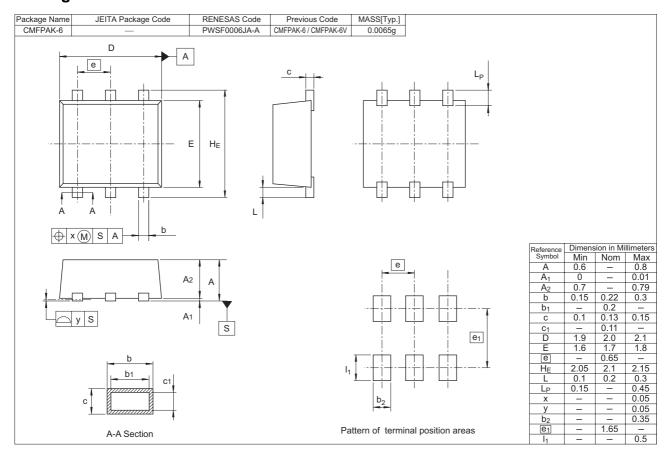
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2240C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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